

Specification Sheet

P/N: MCM-0905S-102Y-H-RU

Products: Certifications:

Molded Power Chokes ISO9001

Multilayer Chip Inductors IATF16949

<u>Lan Transformer</u> ISO14001

RF Passive / Antennas QC080000

Automotive

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REVISIONS

REV.	Description	Date	Approvaled by	Checked by	Checked by	Prepared by
00	Issue	2018.03.19	Vincent	Marco	Sara	Stanley



I.SCOPE:

This specification applies to the Pb Free high current type SMD Common mode filter for MCM-0905S-102Y-H-□□

PRODUCT INDENTIFICATION

<u>MCM</u> - <u>0905S</u> - <u>102</u> <u>Y</u> - H - <u>□</u><u>-RU</u>

- 1
- 2
- 34
- (5)
- ① Product Code
- 2 Dimensions Code
- **3 Impedance Code**
- 4 Tolerance
- **(5) Inner Control Code**

Π . INDEX:

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Unless otherwise specified, test condition should be Temp. = 20 ± 5 °C,

Humidity=35~85%

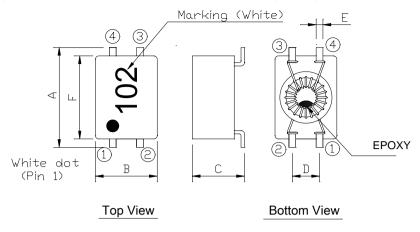
But if needed, then test condition should be Temp.=20±2℃,

Humidity=65±5%

8.SHELF LIFE

Storage Condition:The temperature should be within-40°C ~105°C and humidity should be less than 75%RH. The product should be used within 12 months from the time of delivery. In addition, suggest to use product within 6 months from the time of delivery.

(1) SHAPES AND DIMENSIONS(mm)



A: 8.90 ±0.50
B: 5.40 ±0.30
C: 5.00 Max.
D: 2.54 ±0.30
E: 0.50 Typ.

F: 7.30 ±0.30

(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L : HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

I.R : CHROMA MODEL 19073 AC/DC/IR HIPOT TESTER (or equivalent)

(3) CHARACTERISTICS

(3)-1 Operate temperature range -40° C $\sim +125^{\circ}$ C (Including self temp. rise)

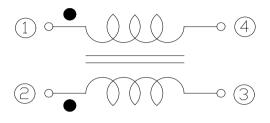
(3)-2 Storage temperature range -40% \sim +125%

TABLE 1

MAGLAYERS PT/NO.	L(1-4),(2-3) (uH) @100KHz/0.25V	Resistance RDC (Ω) Max. (1 line)	Rated Current (A) Max.	Insulation Resistance (MΩ) Min.	Rated Voltage (V) Max.	Marking
MCM-0905S-102Y-H-□□-RU	1000±50%	0.15	1.2	100	80	●102

Rated Current : Based on temperature rise ($\triangle T : 40^{\circ}C$ Typ.)

CIRCUIT DIAGRAM



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS		
Solder ability	The product shall be connected to the test	Apply cream solder to the printed circuit board .		
	circuit board by the fillet (the height is 0.2mm).	Refer to clause 8 for Reflow profile.		
Resistance to	There shall be no damage or problems.	Temperature profile of reflow soldering		
Soldering heat		© 300— soldering (Peak temperature 260±3°€ 10 sec)		
(reflow soldering)		φ 250— (Feak temperature 20023 € 10 sec.)		
		(Peak temperature 260±3°C 10 sec) ### 250 ###		
		Pre-heating (230+0°C)		
		Slow cooling (Stored at room		
		1 1/ 1		
		50 -		
		2 min 10 sec. 2 min. or more		
		The specimen shall be passed through the reflow oven		
		with the condition shown in the above profile for 1 time.		
		The specimen shall be stored at standard atmospheric		
		eric conditions for 1 hour, after which the measurement		
		shall be made.		
Terminal strength	The terminal electrode and the ferrite must	Solder a chip to test substrate , and then laterally apply		
	not damaged.	a load 9.8N in the arrow direction.		
		Printed circuit board		
Strength on PC board	The terminal electrode and the ferrite must	Solder a chip to test substrate and then apply a load.		
bending	not damaged.			
		Test board:FR4 100×40×1mm		
		R10 ~ Fall speed:1mm/sec.		

		Dimensions in mm		
High	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit		
temperature	Insulation resistance and DC resistance on the	board,the test shall be done.		
resistance	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.		
	The terminal electrode and the ferrite must not	Temperature : +125±2℃		
	damaged.	Applied voltage : Rated voltage		
		Applied current : Rated current		
		Testing time : 500±12 hours		



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
resistance	Insulation resistance and DC resistance on the	board,the test shall be done.
	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must not	Temperature : +60±2℃ , Humidity : 90 to 95 %RH
	damaged.	Applied voltage : Rated voltage
		Applied current : Rated current
		Testing time : 500±12 hours
Thermal shock	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	1 cycle +125°C 30 min. 30 sec -40°C 30 min. Testing Time:100 cycle
Low	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test
temperature	Insulation resistance and DC resistance on the	circuit board,the test shall be done.
storage	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
5.0.25	The terminal electrode and the ferrite must	Temperature : -40±2℃
	not damaged.	Testing time : 500±12 hours
Vibration	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	After the samples shall be soldered onto the test circuit board,the test shall be done. Frequency: 10 to 55 Hz Amplitude: 1.52 mm Dimension and times: X,Y and Z directions for 2 hours each.
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated over the whole of the sample before hard, the sample shall then be preheated for about 2 minutes in a temperature of 130~150°C and after it has been immersed to a depth 0.5mm below for 3±0.2 seconds fully in molten solder M705 with a temperature of 245±2°C. More than 75% of the electrode sections shall be couered with new solder smoothly when the sample is taken out of the solder bath.

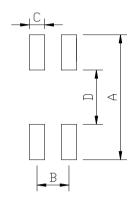


(5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS(mm)

(STANDARD PATTERN)

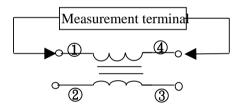


A: 10.50 B: 2.54 C: 1.20 D: 4.50

(6) TEST EQUIPMENT

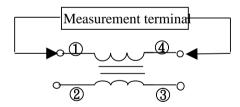
(6)-1 Inductance

Measured by using HP4284A



(6)-2 DC Resistance

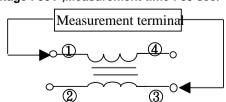
Measured by using Chroma 16502 milliohm meter.



(6)-3 Insulation Resistance

Measured by using Chroma 19073

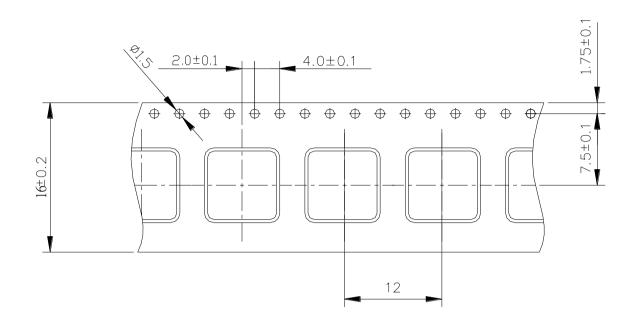
Measurement voltage: 50V, Measurement time: 60 sec.



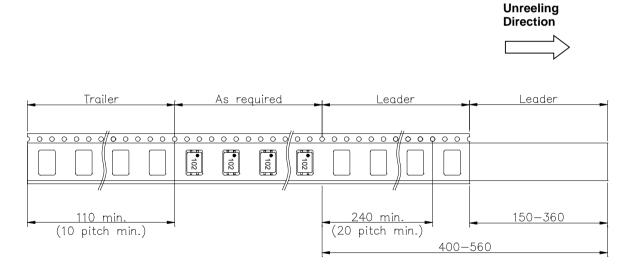


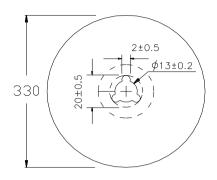
(6) PACKAGING

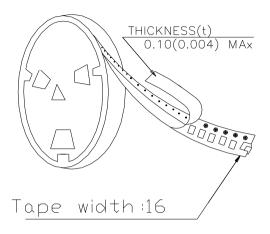
(6)-1 CARRIER TAPE DIMENSIONS (mm)



(6)-2 TAPING DIMENSIONS (mm)







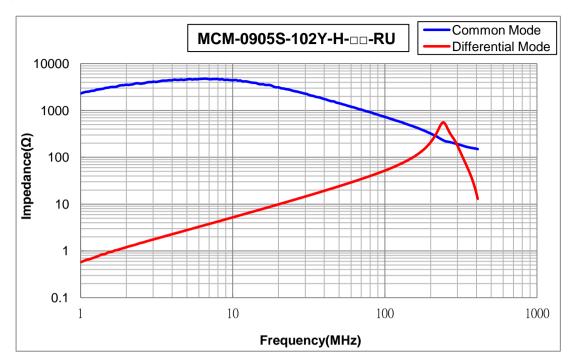
(b)-4 QUANIII Y

1000 pcs/Reel

The products are packaged so that no damage will be sustained.

TYPICAL ELECTRICAL CHARACTERISTICS

Impedance VS. Frequency



Temperature VS. DC Current

